

To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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HAT3010R

Silicon N / P Channel Power MOS FET
High Speed Power Switching

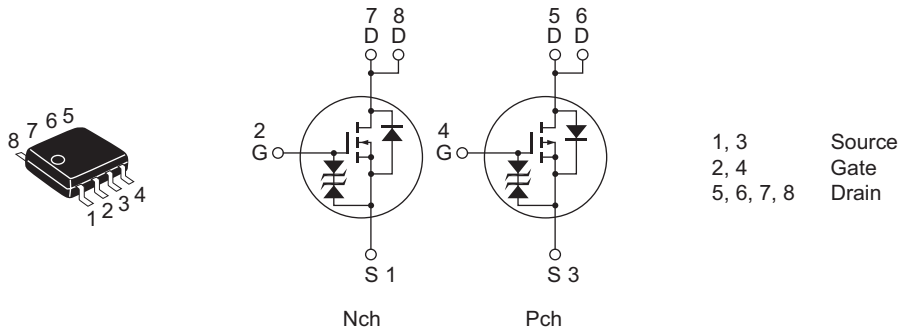
REJ03G1199-1000
(Previous: ADE-208-1402H)
Rev.10.00
Sep 07, 2005

Features

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting

Outline

RENESAS Package code: PRSP0008DD-D
(Package name: SOP-8 <FP-8DAV>)



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value		Unit
		Nch	Pch	
Drain to source voltage	V_{DSS}	60	-60	V
Gate to source voltage	V_{GSS}	±20	±20	V
Drain current	I_D	6	-5	A
Drain peak current	$I_{D(pulse)}$ ^{Note 1}	48	-40	A
Body-drain diode reverse drain current	I_{DR}	6	-5	A
Channel dissipation	P_{ch} ^{Note 2}	2	2	W
Channel dissipation	P_{ch} ^{Note 3}	3	3	W
Channel temperature	T_{ch}	150	150	°C
Storage temperature	T_{stg}	-55 to +150	-55 to +150	°C

Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$ 2. 1 Drive operation: When using the glass epoxy board (FR4 40 × 40 × 1.6 mm), $PW \leq 10 s$ 3. 2 Drive operation: When using the glass epoxy board (FR4 40 × 40 × 1.6 mm), $PW \leq 10 s$

Electrical Characteristics

N Channel

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	$I_D = 10 \text{ mA}$, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	$I_G = \pm 100 \mu A$, $V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	±10	μA	$V_{GS} = \pm 16 \text{ V}$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 60 \text{ V}$, $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	25	32	mΩ	$I_D = 3 \text{ A}$, $V_{GS} = 10 \text{ V}$ ^{Note 4}
	$R_{DS(on)}$	—	32	45	mΩ	$I_D = 3 \text{ A}$, $V_{GS} = 4.5 \text{ V}$ ^{Note 4}
Forward transfer admittance	$ y_{fs} $	7	11	—	S	$I_D = 3 \text{ A}$, $V_{DS} = 10 \text{ V}$ ^{Note 4}
Input capacitance	C_{iss}	—	1050	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	C_{oss}	—	150	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	90	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	15	—	ns	$V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$
Rise time	t_r	—	15	—	ns	$V_{DD} \cong 30 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	55	—	ns	$R_L = 10 \Omega$
Fall time	t_f	—	10	—	ns	$R_g = 4.7 \Omega$
Body-drain diode forward voltage	V_{DF}	—	0.85	1.10	V	$I_F = 6 \text{ A}$, $V_{GS} = 0$ ^{Note 4}
Body-drain diode reverse recovery time	t_{rr}	—	50	—	ns	$I_F = 6 \text{ A}$, $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu s$

Note: 4. Pulse test

P Channel

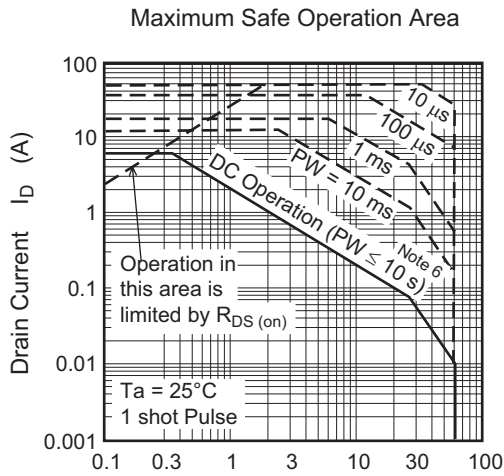
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-60	—	—	V	$I_D = -10 \text{ mA}$, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 20	—	—	V	$I_G = \pm 100 \mu\text{A}$, $V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 16 \text{ V}$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	-1	μA	$V_{DS} = -60 \text{ V}$, $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	—	-2.5	V	$V_{DS} = -10 \text{ V}$, $I_D = -1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	60	76	$\text{m}\Omega$	$I_D = -2.5 \text{ A}$, $V_{GS} = -10 \text{ V}$ ^{Note 5}
	$R_{DS(on)}$	—	90	130	$\text{m}\Omega$	$I_D = -2.5 \text{ A}$, $V_{GS} = -4.5 \text{ V}$ ^{Note 5}
Forward transfer admittance	$ y_{fs} $	3	5	—	S	$I_D = -2.5 \text{ A}$, $V_{DS} = -10 \text{ V}$ ^{Note 5}
Input capacitance	C_{iss}	—	1350	—	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	C_{oss}	—	135	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	85	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	20	—	ns	$V_{GS} = -10 \text{ V}$, $I_D = -2.5 \text{ A}$
Rise time	t_r	—	15	—	ns	$V_{DD} \cong -30 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	55	—	ns	$R_L = 12 \Omega$
Fall time	t_f	—	10	—	ns	$R_g = 4.7 \Omega$
Body-drain diode forward voltage	V_{DF}	—	-0.85	-1.10	V	$I_F = -5 \text{ A}$, $V_{GS} = 0$ ^{Note 5}
Body-drain diode reverse recovery time	t_{rr}	—	50	—	ns	$I_F = -5 \text{ A}$, $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 5. Pulse test

Main Characteristics

N Channel

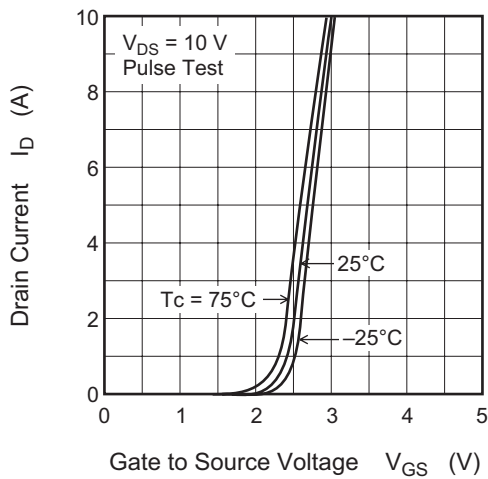


Drain to Source Voltage V_{DS} (V)

Note 6:

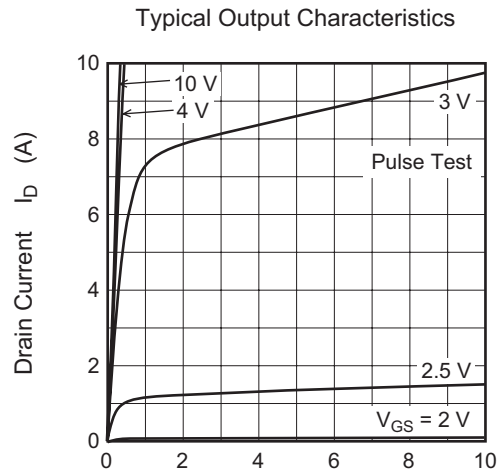
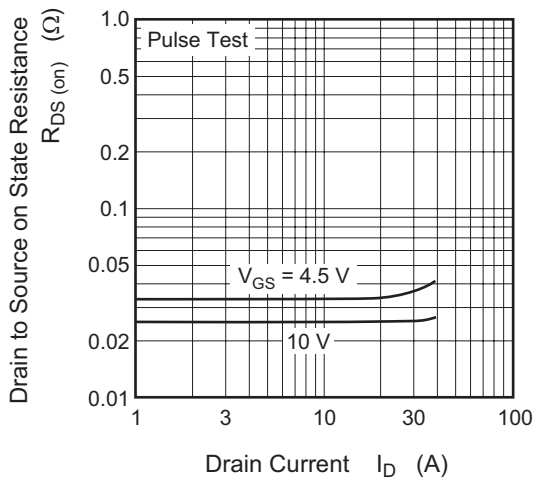
When using the glass epoxy board (FR4 40 × 40 × 1.6 mm)

Typical Transfer Characteristics



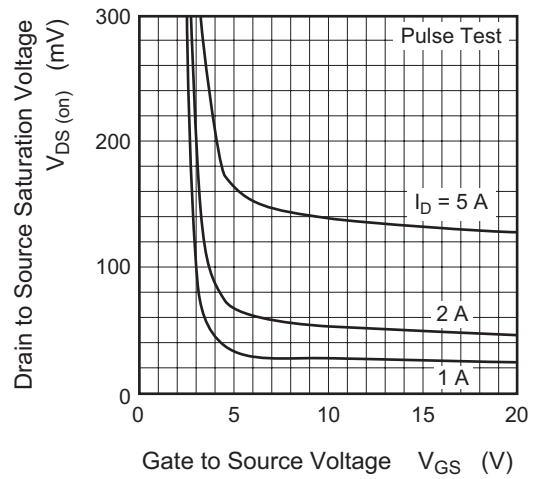
Gate to Source Voltage V_{GS} (V)

Static Drain to Source on State Resistance vs. Drain Current

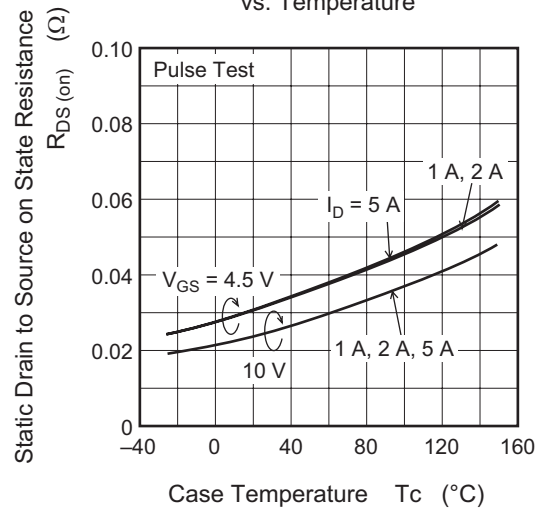


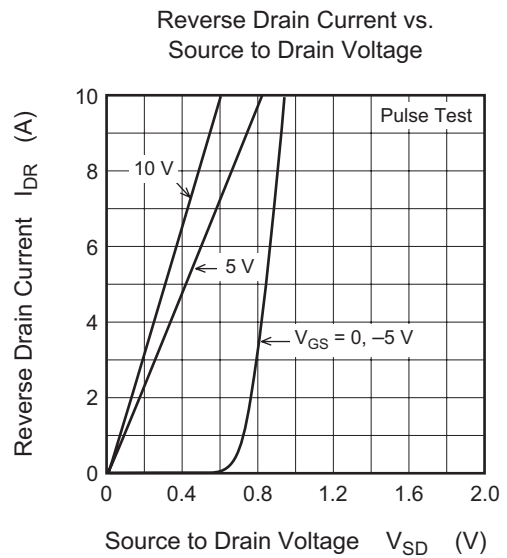
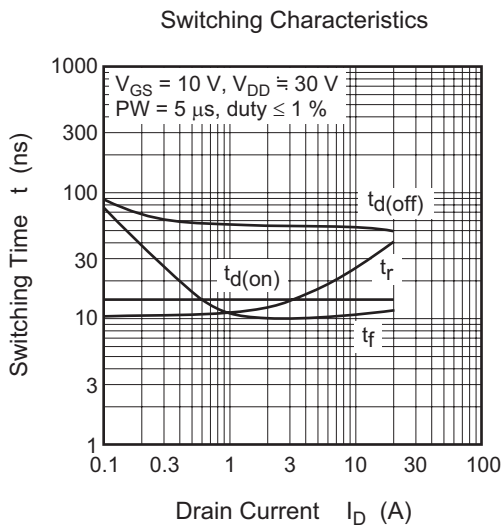
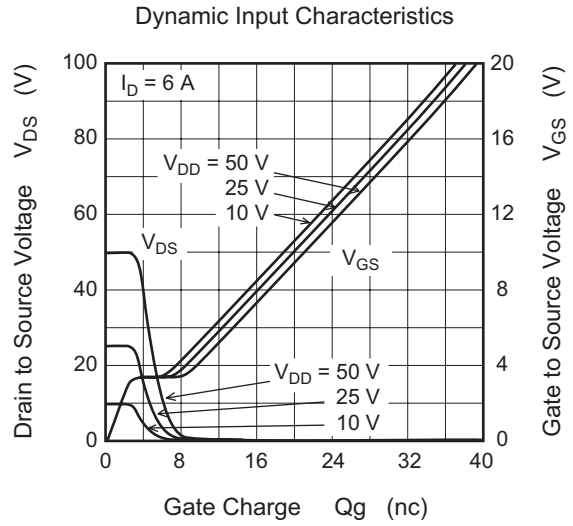
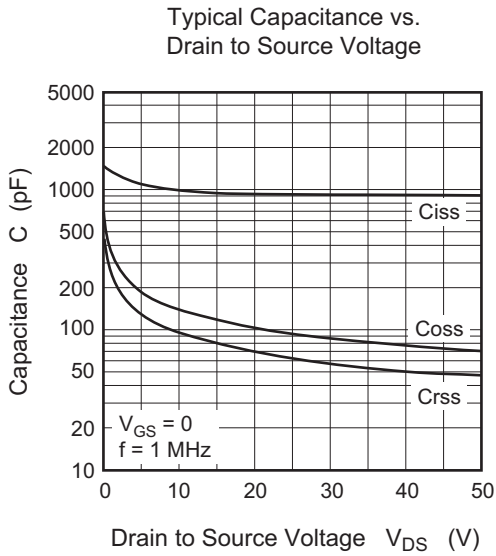
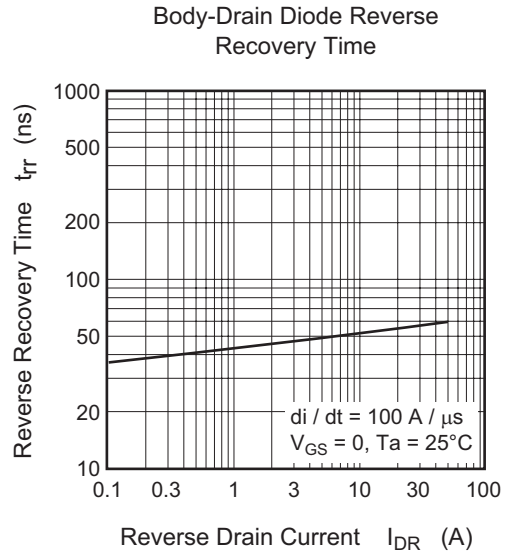
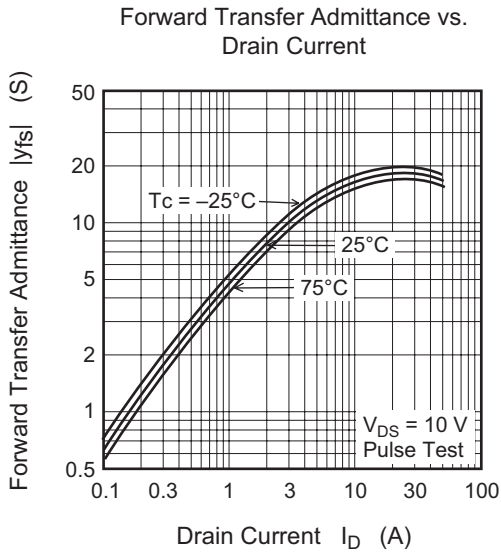
Drain to Source Voltage V_{DS} (V)

Drain to Source Saturation Voltage vs. Gate to Source Voltage



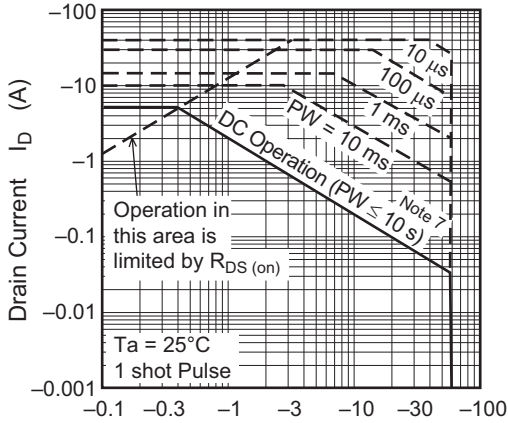
Static Drain to Source on State Resistance vs. Temperature





P Channel

Maximum Safe Operation Area

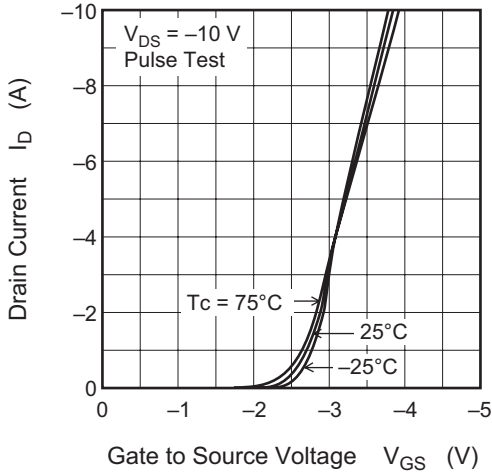


Drain to Source Voltage V_{DS} (V)

Note 7:

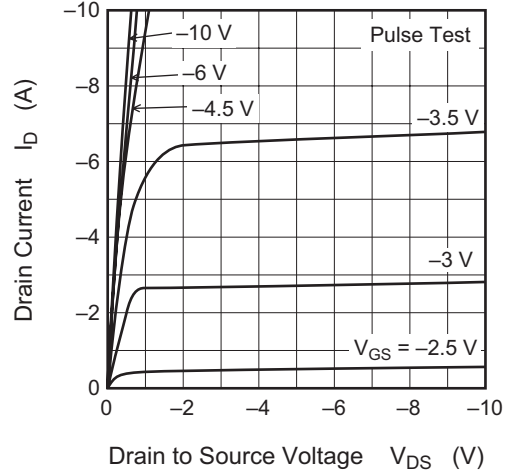
When using the glass epoxy board (FR4 40 × 40 × 1.6 mm)

Typical Transfer Characteristics



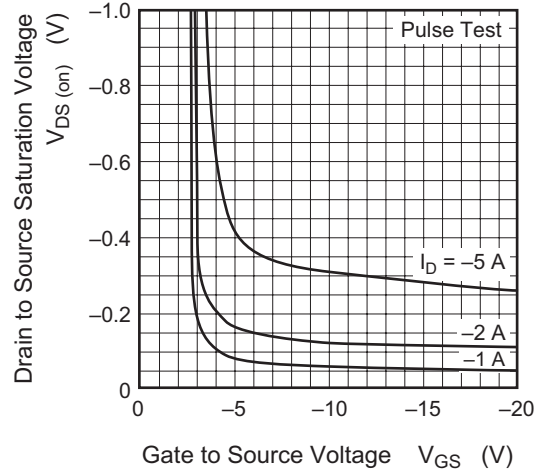
Gate to Source Voltage V_{GS} (V)

Typical Output Characteristics



Drain to Source Voltage V_{DS} (V)

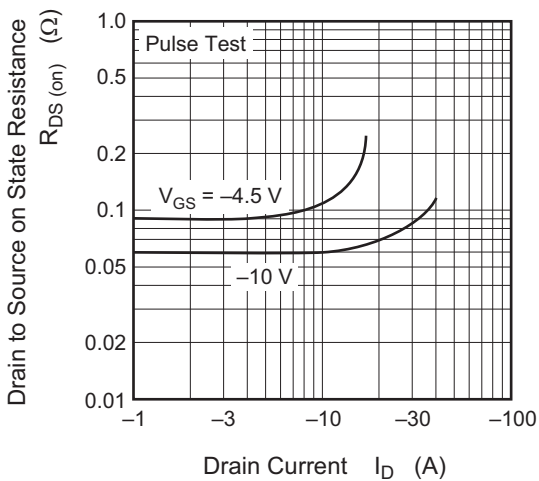
Drain to Source Saturation Voltage vs. Gate to Source Voltage



Drain to Source Saturation Voltage $V_{DS(on)}$ (V)

Gate to Source Voltage V_{GS} (V)

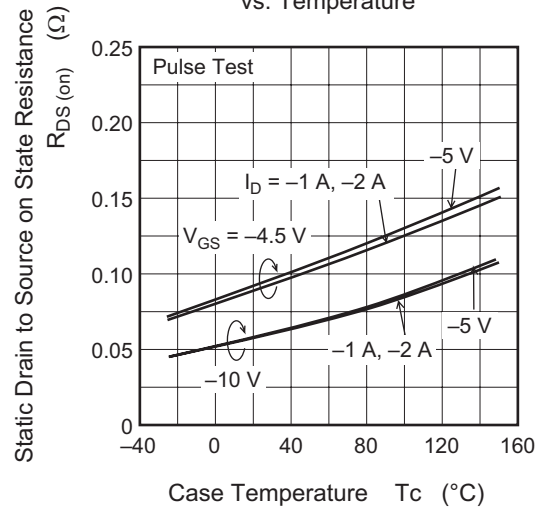
Static Drain to Source on State Resistance vs. Drain Current



Drain to Source on State Resistance $R_{DS(on)}$ (Ω)

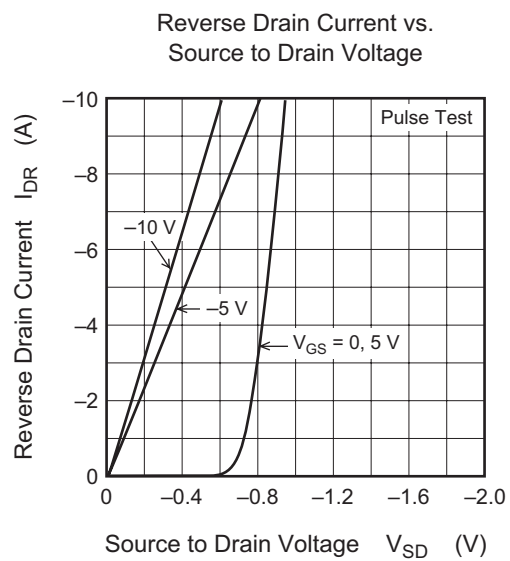
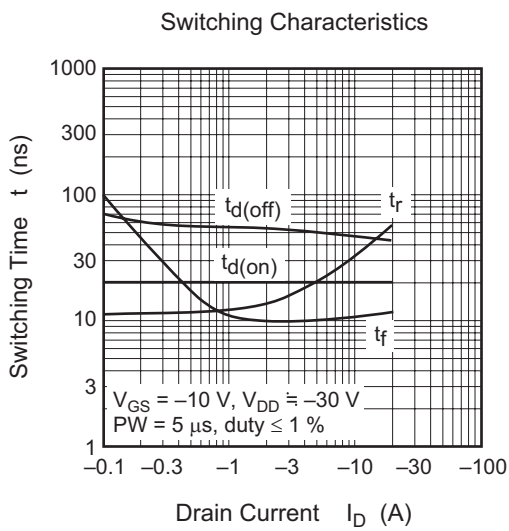
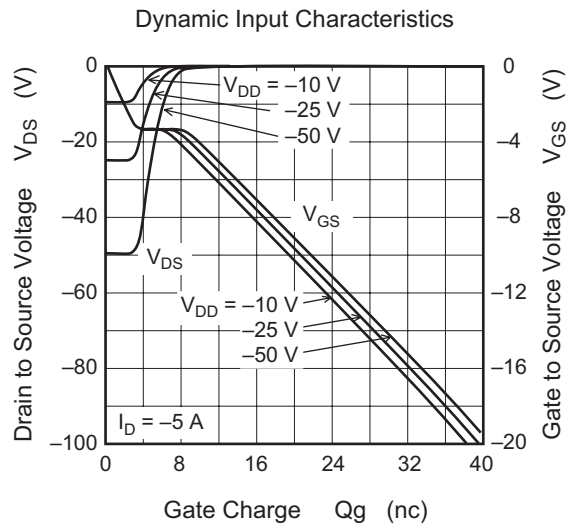
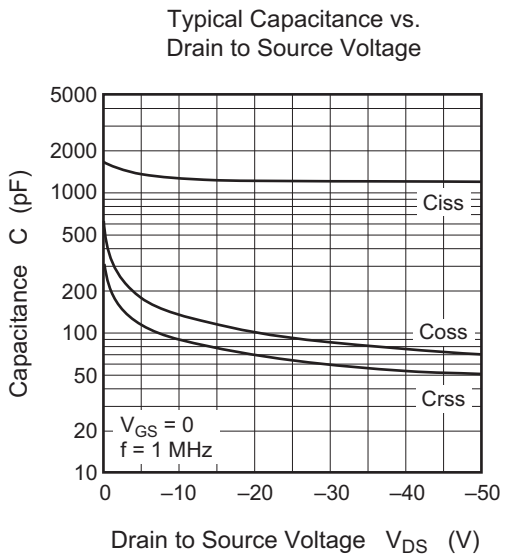
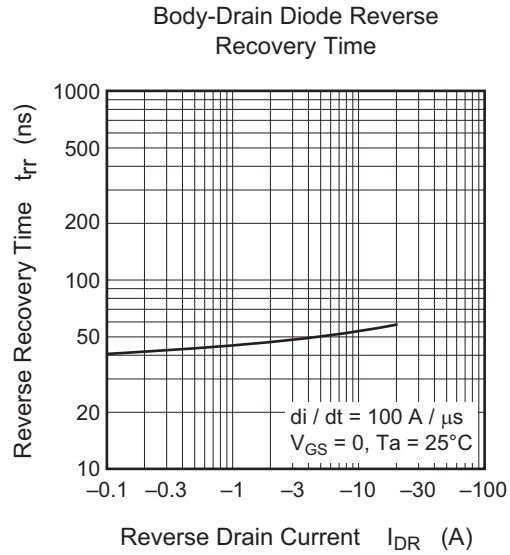
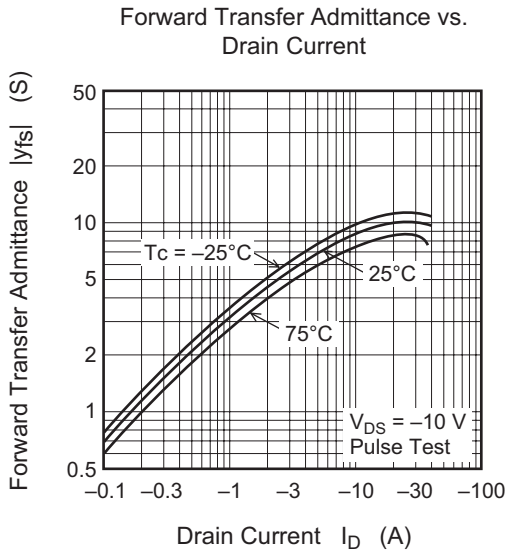
Drain Current I_D (A)

Static Drain to Source on State Resistance vs. Temperature

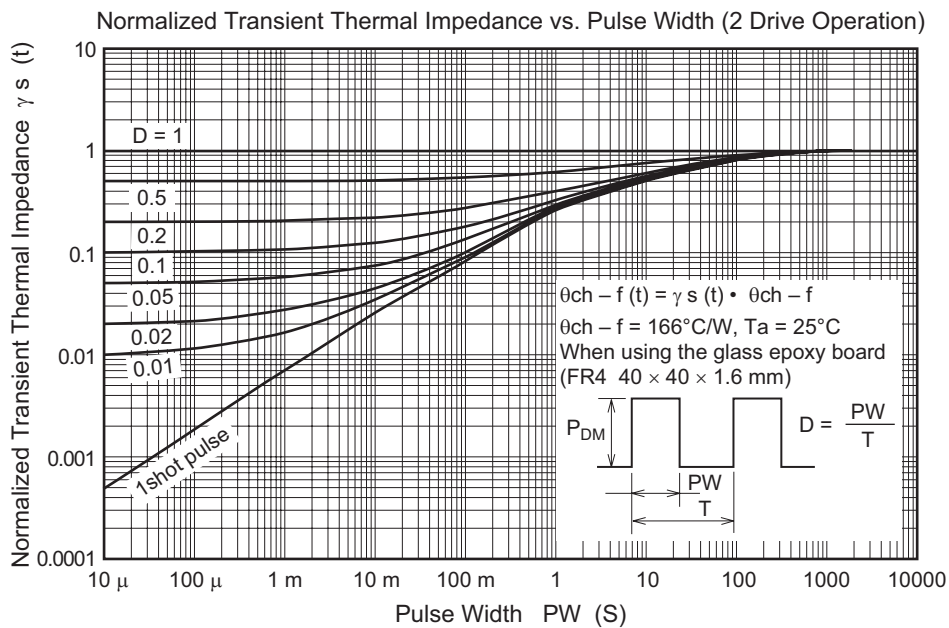
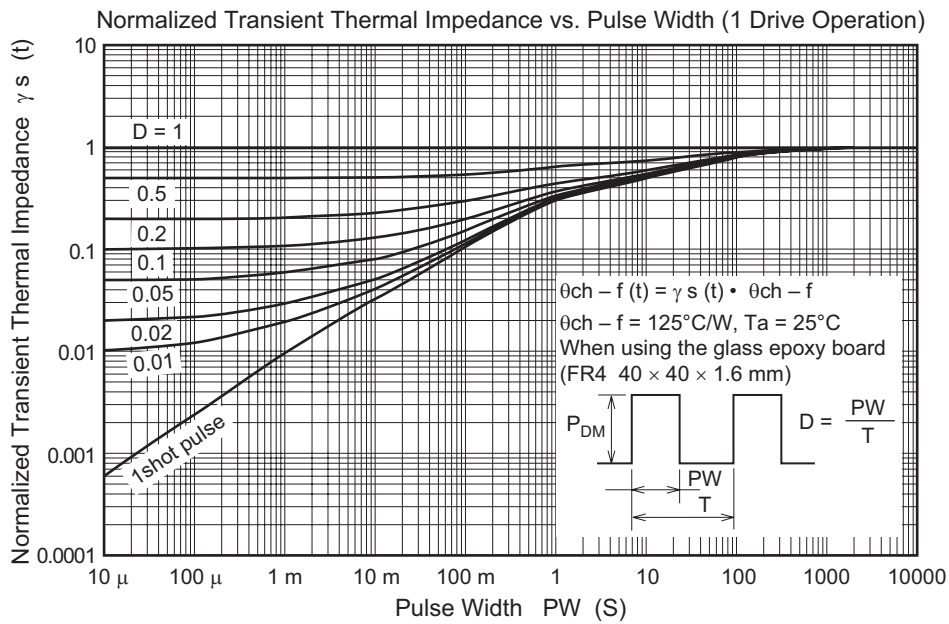
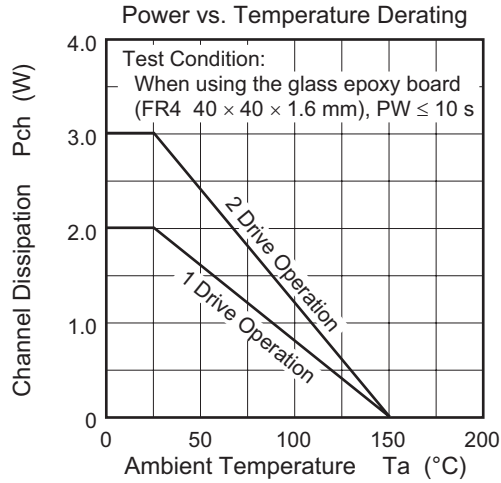


Static Drain to Source on State Resistance $R_{DS(on)}$ (Ω)

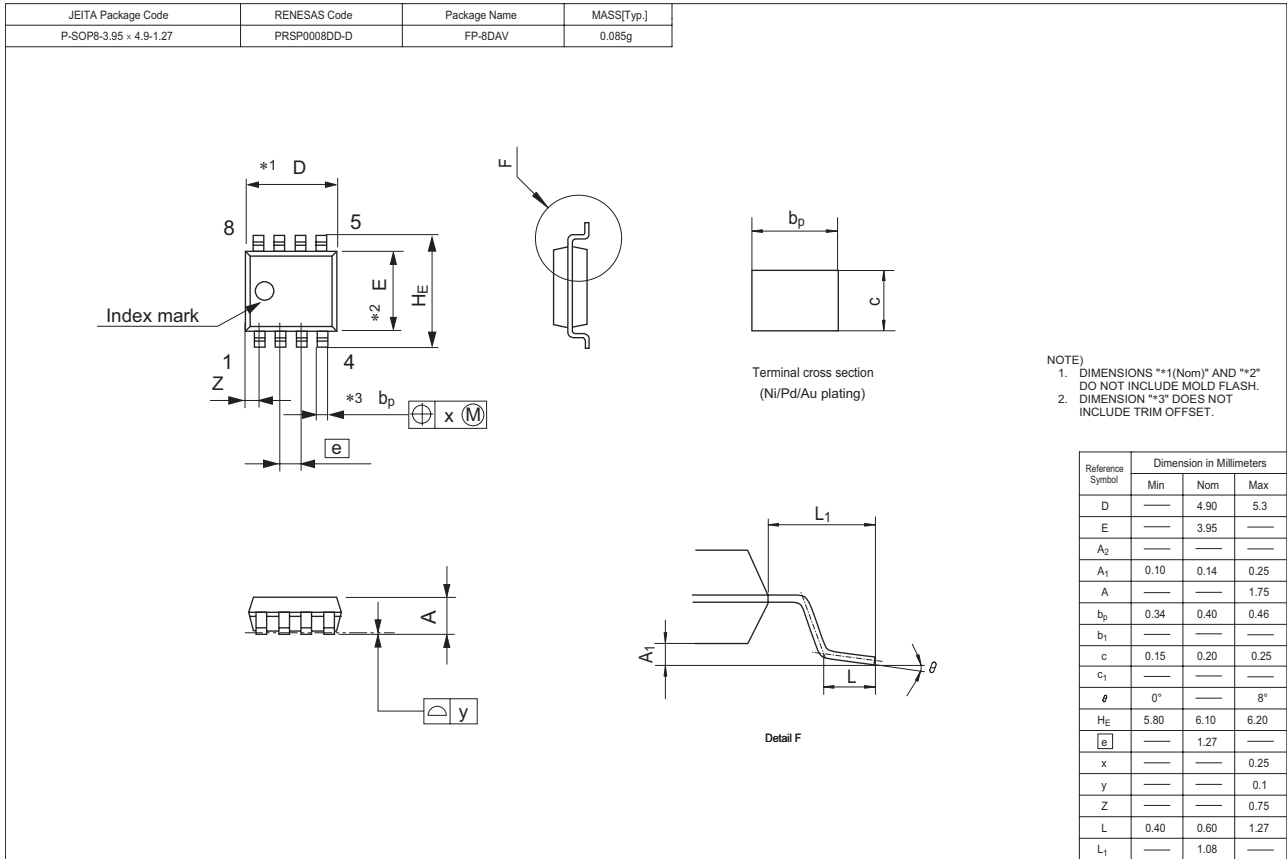
Case Temperature T_c (°C)



Common



Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT3010R-EL-E	2500 pcs	Taping

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[RJK60S3DPP-E0#T2](#) [RJK60S5DPK-M0#T0](#) [APT5010JVFR](#) [APT12031JFLL](#) [APT12040JVR](#) [DMN3404LQ-7](#) [NTE6400](#) [JANTX2N6796U](#)
[JANTX2N6784U](#) [JANTXV2N5416U4](#) [SQM110N05-06L-GE3](#) [SIHF35N60E-GE3](#) [2SK2614\(TE16L1,Q\)](#)